

Amendments to the Claims:

1. (Currently amended) [[A]] An intermediate wafer assembly comprising: a handle wafer; and a bonded wafer comprising a substrate having opposed first and second major surfaces and a peripheral edge extending therebetween, wherein the bonded wafer is attached to said handle wafer such that the first major surface faces away from the handle wafer and the second major surface faces toward the handle wafer, and wherein a cross-sectional profile of the edge comprises:

an angled edge segment adjacent the first major surface that extends linearly at a predefined angle relative to a reference plane defined by the first major surface; and

a curved edge segment that defines a continuous curve extending from the angled edge segment to the second major surface.

2. (Currently amended) [[A]] The intermediate wafer assembly according to Claim 1 wherein the curved edge segment comprises a radiused surface extending from the angled edge segment to the second major surface.

3. (Currently amended) [[A]] The intermediate wafer assembly according to Claim 1 wherein the second major surface has a smaller diameter than a medial portion of said substrate between said first and second major surfaces.

4. (Currently amended) [[A]] The intermediate wafer assembly according to Claim 3 wherein the diameter of the second major surface is between 100 microns and 300 microns smaller than a diameter of ~~that~~ the medial portion of said substrate having the largest diameter.

5. (Currently amended) [[A]] The intermediate wafer assembly according to Claim 1 wherein the first major surface has a smaller diameter than a diameter of the second major surface.

6. (Currently amended) An intermediate wafer assembly comprising:

a handle wafer; and

a bonded wafer attached to said handle wafer, said bonded wafer comprising a first major surface facing away from said handle wafer and a second major surface facing toward said handle wafer, said bonded wafer further comprising an angled edge segment adjacent the first major surface that extends linearly at a predefined angle relative to a reference plane defined by the first major surface,

wherein said handle wafer and said bonded wafer each include a respective edge extending peripherally thereabout, and wherein the edge of each respective wafer defines a radiused surface that extends continuously to an interface between said handle and bonded wafers, wherein the radiused surface of said bonded wafer extends continuously from the angled edge segment to the second major surface.

7. (Currently amended) [[An]] The intermediate wafer assembly according to Claim 6 wherein ~~each~~ said handle wafer comprises opposed major surfaces, and wherein the major surface of each wafer that is proximate the interface has a smaller diameter than a medial portion of the respective wafer between the opposed major surfaces.

8. (Currently amended) [[An]] The intermediate wafer assembly according to Claim 7 wherein the diameter of the major surface of each wafer that is proximate the interface is between 100 microns and 300 microns smaller than a diameter of ~~that~~ the medial portion of the respective wafer having the largest diameter.

9. (Currently amended) [[An]] The intermediate wafer assembly according to Claim 6 wherein ~~each~~ said handle wafer comprises opposed major surfaces, and wherein a cross-sectional profile of the edge of ~~each respective~~ said handle wafer also includes an angled edge segment, adjacent the major surface opposite the interface, that extends linearly at a predefined angle relative to a reference plane defined by the respective major surface.

10. (Currently amended) [[An]] The intermediate wafer assembly according to Claim [[9]] 6 wherein the first major surface of said bonded wafer opposite the interface has a smaller

diameter than a diameter of the second major surface of said bonded wafer proximate the interface.

11. (Original) An intermediate wafer assembly comprising:

a handle wafer; and

a bonded wafer attached to said handle wafer, said bonded wafer having a first major surface facing away from said handle wafer, a second major surface proximate said handle wafer, and a peripheral edge extending between the first and second major surfaces, wherein a cross-sectional profile of the edge comprises:

a first angled edge segment adjacent the first major surface that extends linearly at a predefined angle relative to a reference plane defined by the first major surface;

a second angled edge segment adjacent the second major surface that extends linearly at a predefined angle relative to a reference plane defined by the second major surface, wherein the second angled edge segment is at least 50% smaller in a radial direction than the first angled edge segment such that the diameter of the second major surface is correspondingly larger than the diameter of the first major surface; and

a curved edge segment that defines a continuous curve extending between the first and second angled edge segments.

12. (Currently amended) [[An]] The intermediate wafer assembly according to Claim 11 wherein the curved edge segment of said bonded wafer comprises a radiused surface extending continuously between the first and second angled edge segments.

13. (Currently amended) [[An]] The intermediate wafer assembly according to Claim 11 wherein said handle wafer also has a first major surface facing away from said bonded wafer, a second major surface proximate said bonded wafer, and a peripheral edge extending between the first and second major surfaces, wherein a cross-sectional profile of the edge comprises:

a first angled edge segment adjacent the first major surface that extends linearly at a predefined angle relative to a reference plane defined by the first major surface;

a second angled edge segment adjacent the second major surface that extends linearly at a predefined angle relative to a reference plane defined by the second major surface, wherein the second angled edge segment is at least 50% smaller in a radial direction than the first angled edge segment such that the diameter of the second major surface is correspondingly larger than the diameter of the first major surface; and

a curved edge segment that defines a continuous curve extending between the first and second angled edge segments.

Claims 14-26 (Canceled).